What is claimed is:

1. A test unit comprising:

an air source to generate a substantially constant temperature air stream;

a test fixture to hold a die; and

an enclosure for substantially surrounding the test fixture, the enclosure in operative communication with the air source, the enclosure constructed and arranged for coupling the temperature controlled air stream from the air source to the test fixture, and the enclosure including a non-conductive core comprising a plurality of surfaces, wherein one or more of the plurality of surfaces comprises a conductive coating applied to at least a portion thereof and at least one of the plurality of surfaces contacting the test fixture comprises a substantially uncoated surface.

2. The test unit of claim 1, wherein the non-conductive core comprises fiberglass.

3. The test unit of claim 1, wherein the conductive coating comprises a semiconductor.

4. The test unit of claim 1, wherein the conductive coating comprises a metal.

5. The test unit of claim 4, wherein the metal comprises aluminum.

6. The test unit of claim 1, wherein at least one of the plurality of surfaces has a connector.

7. The test unit of claim 6, wherein the connector comprises a snap-on ground connector.

8. The test unit of claim 1, wherein the uncoated surface has a plurality of locating holes.

9. The test unit of claim 8, wherein the test fixture has a plurality of locating pins and wherein each of the plurality of locating pins is capable of being inserted into at least one of the plurality of locating holes.

10. The test unit of claim 1, wherein the enclosure has one or more vent holes.

11. The test unit of claim 10, wherein the enclosure has a first end and a second end and each of the one or more vent holes is located about half way between the first end and the second end.

12. The test unit of claim 1, wherein the uncoated surface includes at least one substantially chamfered edge.

13. The test unit of claim 12, wherein the at least one substantially chamfered edge is uncoated.

14. A method of preparing a die for testing, the method comprising:

inserting a die in a test fixture having a base;

surrounding the test fixture with an enclosure in operative communication with a substantially constant temperature air stream, the enclosure having one or more exposed surfaces, each of the one or more exposed surfaces being a conductive surface;

coupling each of the one or more exposed surfaces to a source of reference potential; and

allowing the substantially constant temperature air stream to flow through the enclosure and over the die.

15. The method of claim 14, wherein forcing the substantially constant temperature air stream through the enclosure comprises:

injecting an ionized air stream through the enclosure.

16. The method of claim 14, further comprising:

attaching the enclosure to the test fixture; and

forming a substantially air tight coupling between the enclosure and the source of the substantially constant temperature air stream.

17. An enclosure comprising:

a hollow substantially cylindrical insulating core having a first orifice having a first diameter and at least one further orifice, the first orifice constructed and arranged for coupling the interior of the insulating core to a temperature controlled air source and a second orifice constructed and arranged for allowing air entering the core through the first orifice to pass over a test fixture substantially enclosed within the core prior to exiting through the further orifice, the hollow substantially cylindrical insulating core being partially coated with a conductive material maintained at a reference potential relative to the test fixture.

18. The enclosure of claim 17, wherein the hollow substantially cylindrical insulating core comprises fiberglass.

19. The enclosure of claim 17, wherein the first diameter is about 4.5 inches.

20. The enclosure of claim 17, wherein the conductive material comprises a semiconductor.

21. The enclosure of claim 17, wherein the conductive material comprises a metal.

22. The enclosure of claim 21, wherein the metal comprises copper.

23. The enclosure of claim 17, wherein the enclosure has at least two uncoated chamfered edges.

24. A method of fabricating an enclosure, the method comprising:

forming a cylindrically shaped block of insulating material having a substantially flat first end, a substantially flat second end, and an outer surface;

forming a first hole having a first diameter in the cylindrically shaped block to form a first inner surface;

forming a second hole having a second diameter in the cylindrically shaped block to form a second inner surface, the second diameter being greater than the first diameter; and

coating the outer surface, the substantially flat first end, the first inner surface, and the second inner surface with a conductive material.

25. The method of claim 24, wherein coating the outer surface, the first end, the first inner surface, and the second inner surface with a conductive material comprises:

coating the outer surface, the first end, the first inner surface and the second inner surface with aluminum.

26. The method of claim 25, wherein coating the outer surface, the first end, the first inner surface and the second inner surface with aluminum comprises:

depositing the aluminum on the outer surface, the first end, the first inner surface and the second inner surface by chemical vapor deposition.

27. The method of claim 24, wherein coating the outer surface, the first end, the first inner surface, and the second inner surface with a conductive material comprises:

coating the outer surface, the first end, the first inner surface and the second inner surface with a semiconductor.

28. The method of claim 27, wherein coating the outer surface, the first end, the first inner surface and the second inner surface with a semiconductor comprises:

painting the semiconductor on the outer surface, the first end, the first inner surface and the second inner surface.

29. The method of claim 27, wherein coating the outer surface, the first end, the first inner surface and the second inner surface with a semiconductor comprises:

spraying the semiconductor on the outer surface, the first end, the first inner surface and the second inner surface.